

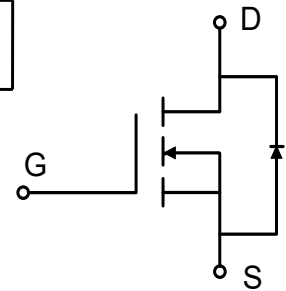
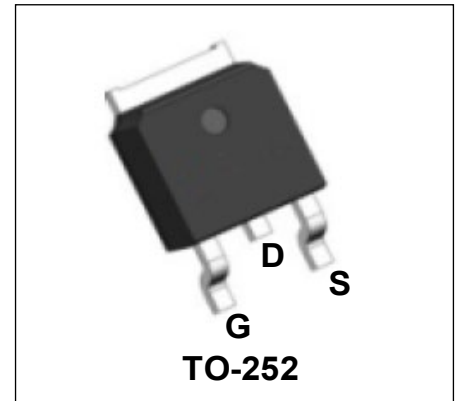
## 150V N-Channel Enhancement Mode Power MOSFET

## Description

WMO09N15T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## Features

- $V_{DS} = 150V$ ,  $I_D = 8.6A$   
 $R_{DS(on)} < 300m\Omega$  @  $V_{GS} = 10V$
- Fully Characterized Avalanche Voltage and Current
- Low Gate Charge
- Excellent Package for Good Heat Dissipation



## Applications

- Power Switching Application
- Hard Switched and High Frequency Circuits

Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	150	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	8.6	A
	$T_C = 100^\circ C$		5.4	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	35	A
Single Pulse Avalanche Energy <sup>2</sup>		$E_{AS}$	1.25	mJ
Total Power Dissipation	$T_C = 25^\circ C$	$P_D$	39	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	65	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	3.2	$^\circ C/W$

**Electrical Characteristics ( $T_J = 25^{\circ}\text{C}$ , unless otherwise noted)**

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	150	-	-	V
Gate-body Leakage current		I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	I <sub>DSS</sub>	V <sub>DS</sub> = 150V, V <sub>GS</sub> = 0V	-	-	1	μA
	T <sub>J</sub> =100°C			-	-	100	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.5	2	2.5	V
Drain-Source on-Resistance <sup>4</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A	-	245	300	mΩ
Forward Transconductance <sup>4</sup>		g <sub>fs</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 4A	-	25	-	S
Dynamic Characteristics <sup>5</sup>							
Input Capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 75V, V <sub>GS</sub> =0V, f =1MHz	-	450	-	pF
Output Capacitance		C <sub>oss</sub>		-	23	-	
Reverse Transfer Capacitance		C <sub>rss</sub>		-	14	-	
Gate Resistance		R <sub>g</sub>	f =1MHz	-	1.5	-	Ω
Switching Characteristics <sup>5</sup>							
Total Gate Charge		Q <sub>g</sub>	V <sub>GS</sub> = 10V,V <sub>DS</sub> = 75V, I <sub>D</sub> =1.5A	-	8.2	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	1.5	-	
Gate-Drain Charge		Q <sub>gd</sub>		-	2.2	-	
Turn-on Delay Time		t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =75V, R <sub>G</sub> = 6Ω, I <sub>D</sub> = 1A,R <sub>G</sub> = 75Ω	-	8.2	-	ns
Rise Time		t <sub>r</sub>		-	10.2	-	
Turn-off Delay Time		t <sub>d(off)</sub>		-	20.5	-	
Fall Time		t <sub>f</sub>		-	15.3	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>4</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current	T <sub>C</sub> =25°C	I <sub>S</sub>	-	-	-	8.6	A

**Notes:**

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^{\circ}\text{C}$ .
2. The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 5A$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

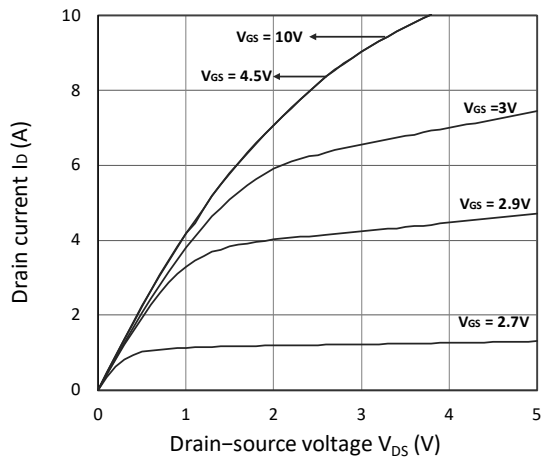


Figure 1. Output Characteristics

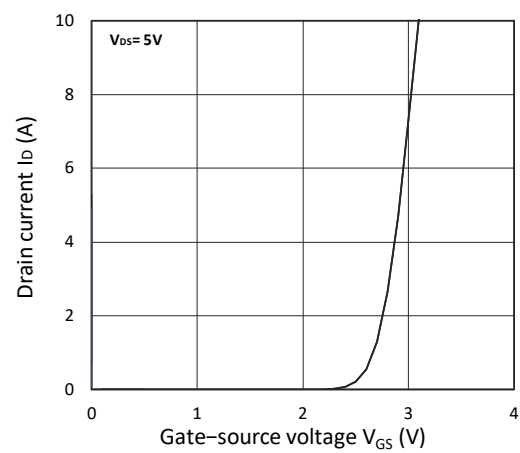


Figure 2. Transfer Characteristics

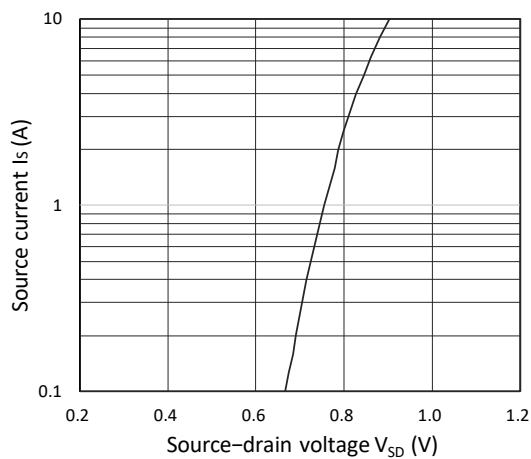
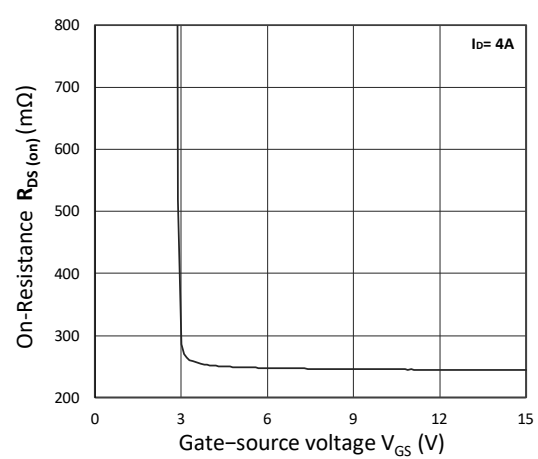
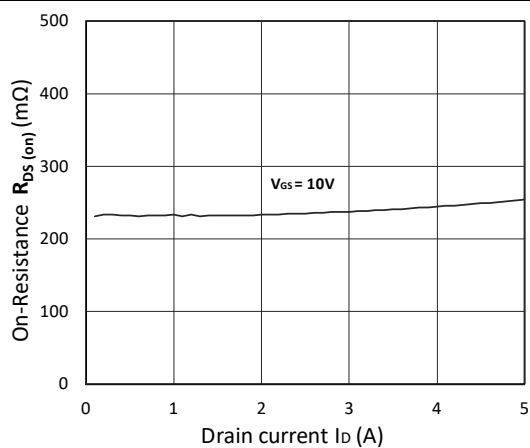
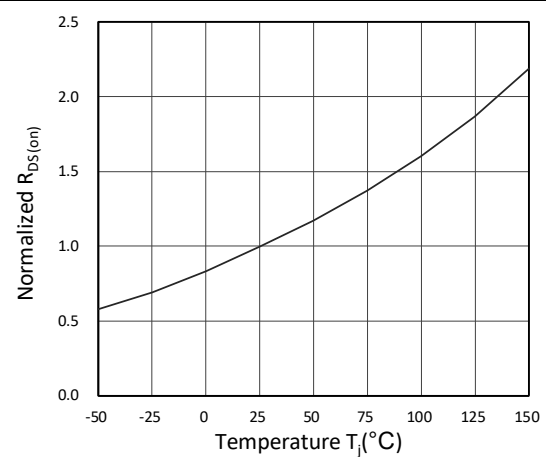


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

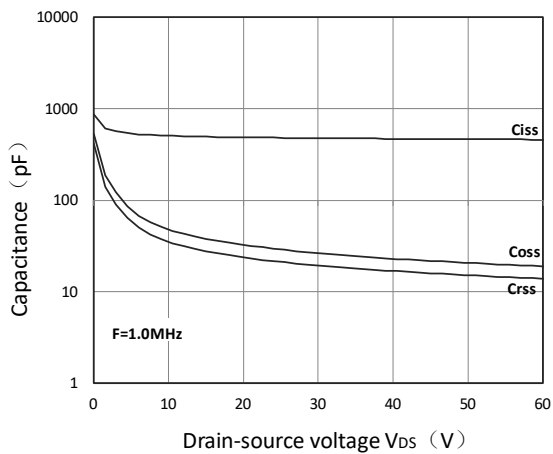


Figure 7. Capacitance Characteristics

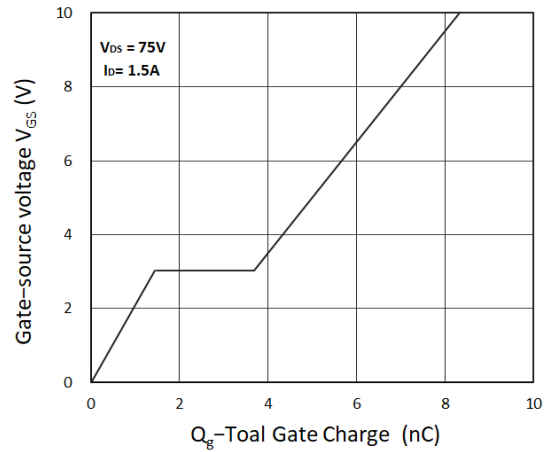


Figure 8. Gate Charge Characteristics

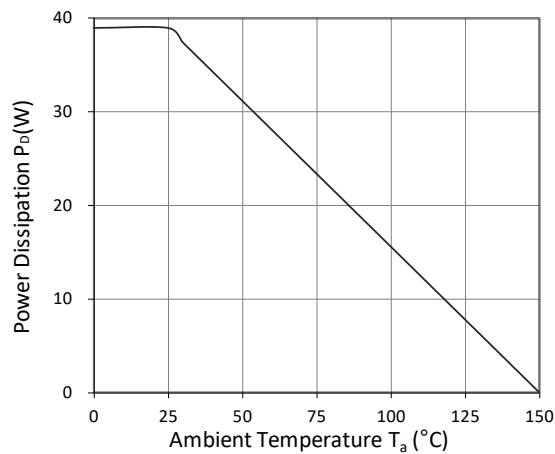


Figure 9. Power Dissipation

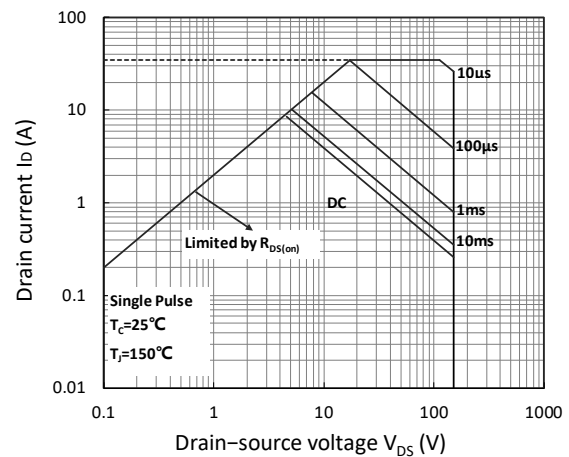


Figure 10. Safe Operating Area

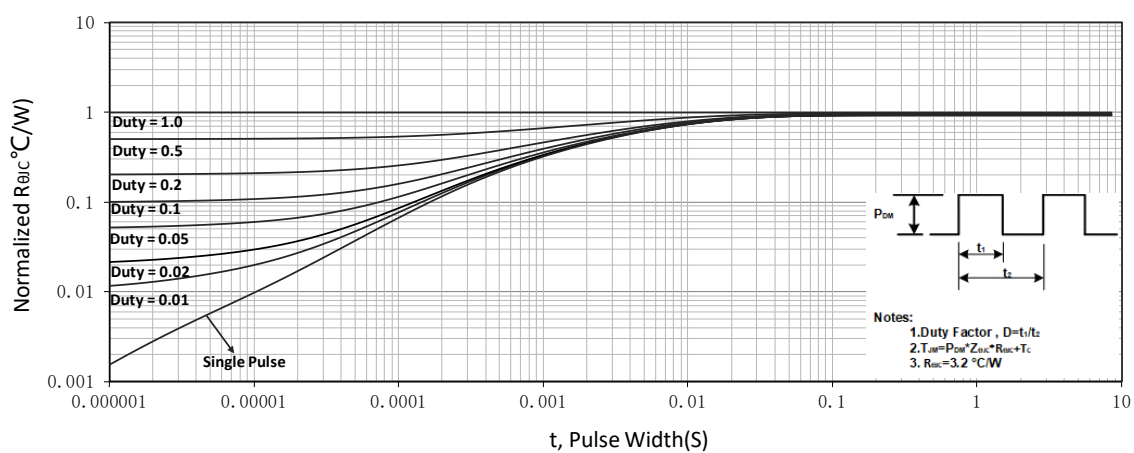


Figure 11. Normalized Maximum Transient Thermal Impedance

## Test Circuit

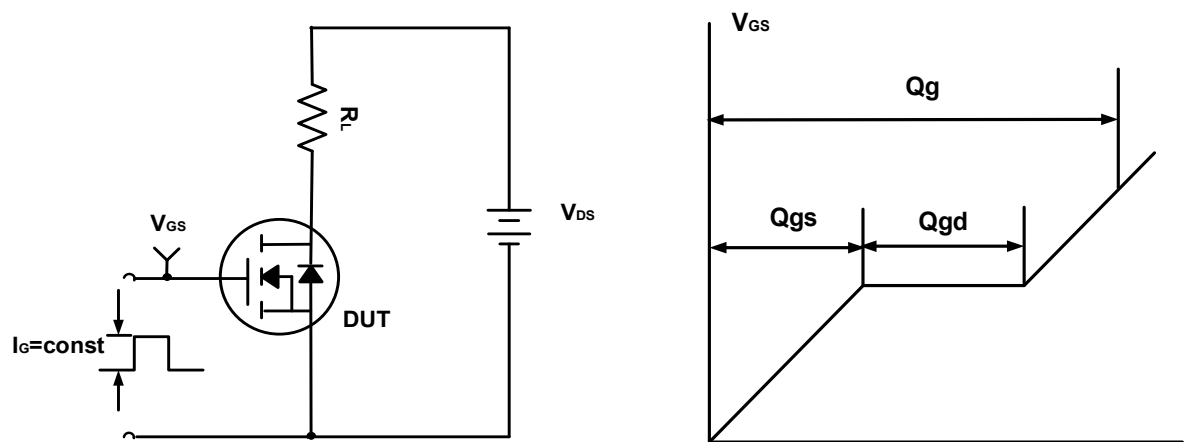


Figure A. Gate Charge Test Circuit &amp; Waveforms

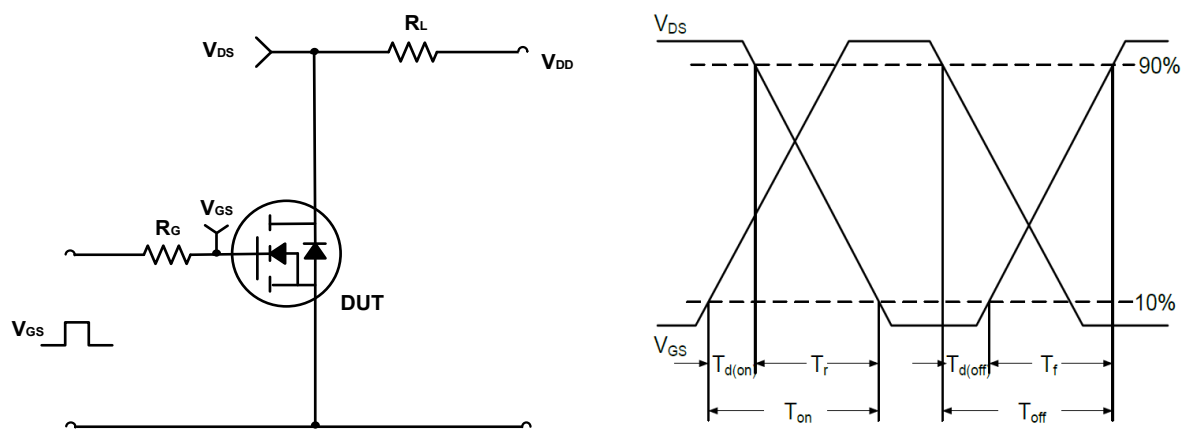


Figure B. Switching Test Circuit &amp; Waveforms

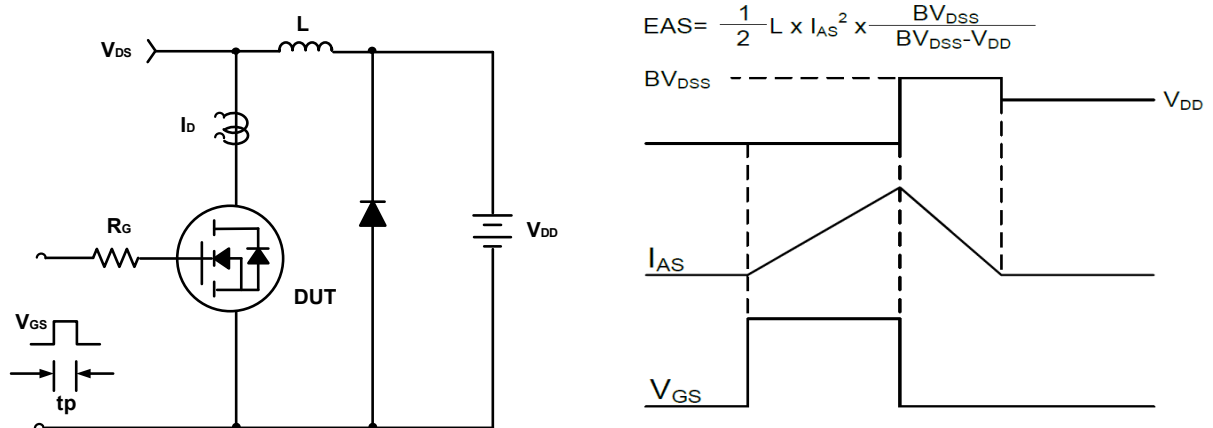
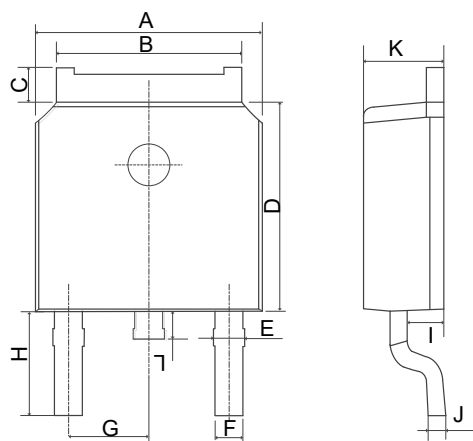


Figure C. Unclamped Inductive Switching Circuit &amp; Waveforms

## Mechanical Dimensions for TO-252



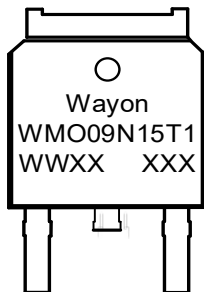
## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
E	0.68	1.10
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00

## Ordering Information

Part	Package	Marking	Packing method
WMO09N15T1	TO-252	WMO09N15T1	Tape and Reel

## Marking Information



WMO09N15T1 = Device code

WWXX XXX= Date code

## Contact Information

No.1001, Shiwan(7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-50310888 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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